

Overview

The purpose of this notice is to announce the addition of Toshiba Corporation as an additional source of supply for Virtex™-4 LX devices.

Description

Starting in 2005, Xilinx Corporation will begin shipping devices manufactured on a 90 nm process from Toshiba, giving Xilinx increased capacity to support Virtex-4 LX production devices. Adding this additional foundry reduces supply chain risks while ensuring a stable supply of devices.

Products Affected

All Virtex-4 LX devices are now manufactured at Toshiba with a select few also manufactured at UMC. The XC4VLX25, XC4VLX60, XC4VLX100, XC4VLX160, and XC4VLX200 devices are shipped interchangeably from either Toshiba or UMC. Devices from both wafer foundries are tested using the same test program and conform to the same data sheet performance specifications.

Traceability

Toshiba devices are identified with the letter N as shown in [Figure 1](#):



XCN05005_01_030306

Figure 1: Package Top Mark Example

Response

No response is required. For additional information or questions, please contact [Xilinx Technical Support](#).

Important Notice: Xilinx Customer Notices (XCNs, XDNs, and Quality Alerts) can be delivered via e-mail alerts sent by the MySupport website (<http://www.xilinx.com/support>). Register today and personalize your “MyAlerts” area to include Customer Notices. This change provides many benefits, including the ability to receive alerts for new and updated information about specific products, as well as alerts for other publications such as data sheets, errata, application notes, etc. For information on how to sign up, refer to [Xilinx Answer Record 18683](#).

For more information on the Xilinx Stepping Methodology, refer to [Xilinx Answer Record 20947](#).

Revision History

The following table shows the revision history for this document.

Date	Version	Revision
02/28/05	1.0	Initial Xilinx release.
03/09/06	1.1	Updated Products Affected paragraph to include XC4VLX160 as a dual source.